



Schedule of Scope to Certificate of Approval Approved Process - Capability Approval

IECQ Certificate No.: C-IECQ BSI 15.0001

CB Certificate No.: 026/QCA

Schedule Number: IECQ-C BSI 15.0001-S Rev No.: 9 Revision Date: 2015/02/01 Page 1 of 1

Board Types:	Rigid Multilayer			BS 123300-003
	Rigid double-sided with plated through holes			BS 123200-003
	Rigid single & double-sided with plain holes			BS 123100-003
	Flex-Rigid multilayer with through holes			BS 123600-003
Base Materials:	Epoxide Woven Glass			
	Polyimide Film			
Board Size:	495.30 mm x 419.10 mm multilayer			BS 123300-003
	261.87 mm x 322.33 mm multilayer			BS 123600-003
Number of Layers	32 maximum			BS 123300-003
	10 maximum			BS 123600-003
Conductors	0.10 mm (photomech) Tolerance -0.02 mm +0.03 mm			
Plated-through Hole Diameter:	0.20 mm	Minimum	Finished hole size	BS 123300-003
	0.80 mm	Minimum	Finished hole size	BS 123600-003
Aspect Ratio:	16.4 : 1	Maximum		BS 123300-003
	2.27 : 1	Maximum		BS 123600-003
Finishes:	* Hot Air Solder Levelling			
	Immersion Silver			
	2.5µm Gold over Copper Edge Contacts			
	Liquid Photopolymer Solder Resist			
	Legend; UV or Oven Cured			
	Solder resist UV cured			
Additional:	Selective Electroplated Gold (2.5 µm) on Copper			
	Selective Electroless Gold (0.07 µm) on Nickel			

* This finish meets the Solderability requirements

This schedule is only valid in conjunction with the referenced Certificate of Approval
This approval and any schedule(s) may only be reproduced in full.
This approval is not transferable and remains the property of the issuing body.
The Status and authenticity of this approval and any schedule(s) may be verified by visiting the
Official IECQ Website. www.iecq.org

BSI, Kitemark Court Davy Avenue Knowlhill Milton Keynes MK5 8PP UK

